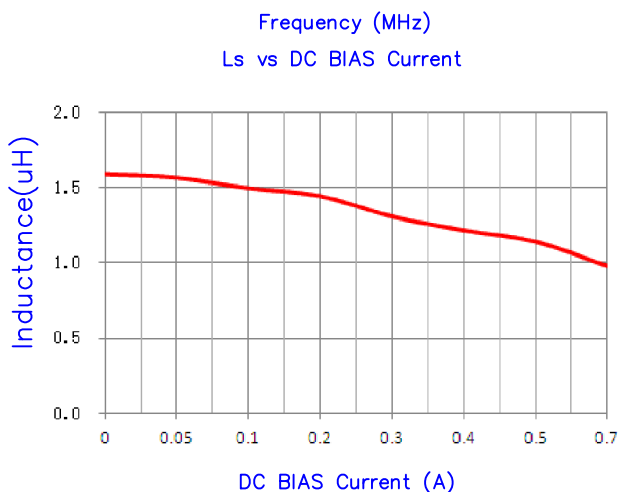
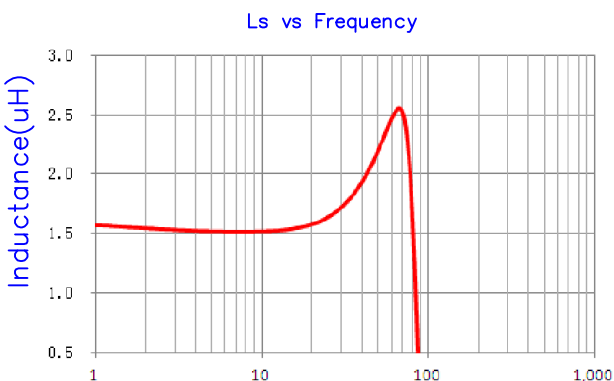
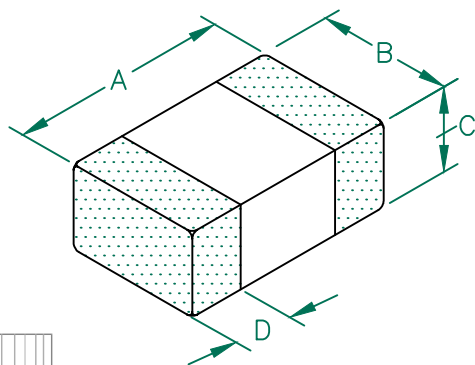


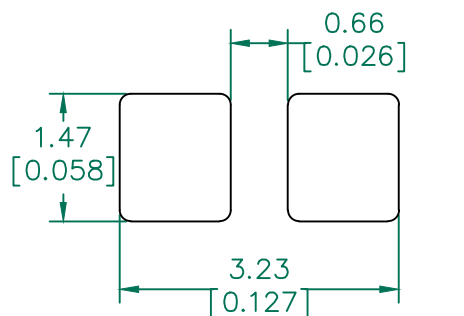
# CPI0805G1R5R-10

## PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.10 [.004]
D	0.50 [.020]	+ 0.20 [.008]



## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)



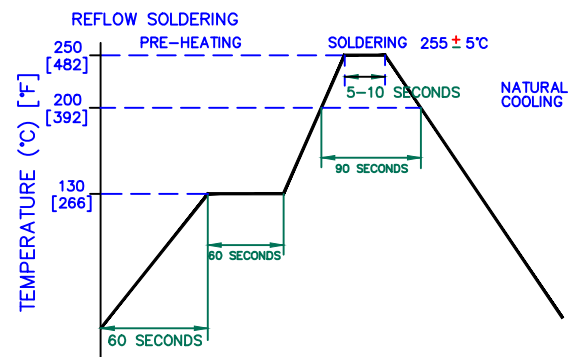
## ELECTRICAL CHARACTERISTICS:

	L ( $\mu$ H) @ 1MHz $\pm 20\%$	DCR ( $\Omega$ )	I (Max)
Nom	1.5		
Min	1.2		
Max	1.8	0.275	700mA

## NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. Operation Temperature TEMP: -55°C~+125°C. (INCLUDING SELF-HEATING)
6. COSMETIC SPECIFICATION REFER TO WI-QA-124.

## RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
				<b>Laird</b>			
				PROJECT/PART NUMBER: <b>CPI0805G1R5R-10</b>			
				REV: <b>C</b> PART TYPE: <b>CO-FIRE</b> DRAWN BY: <b>QU</b>			
<b>C</b> CHANGE PLASTIC TAPE TO PAPER TAPE 04/17/14 QU				DATE: 03/01/11 SCALE: <b>NTS</b> SHEET: <b>1 of 1</b>			
<b>B</b> UPDATE LAIRD LOGO AND NOTES 5 08/05/13 QU				TOOL # <b>-</b>			
<b>A</b> ORIGINAL DRAFT 03/01/11 QU				CAD # <b>-</b>			
REV DESCRIPTION DATE INT				CPI0805G1R5R-10-C			